

IN THE CLAIMS

1-137. (Canceled)

138. (Previously Presented) A processing method, comprising:

exposing a first surface of a first substrate to a plasma;

cleaning said first surface after exposure to said plasma;

terminating said first surface with a chemical species after said cleaning step; and

bonding said first surface to a second surface of a second substrate after said

terminating step.

139. (Previously Presented) A method as recited in claim 138, wherein terminating comprises:

immersing said first surface in a solution.

140. (Previously Presented) A method as recited in claim 138, wherein terminating comprises:

immersing said first surface in an N-based solution.

141. (Previously Presented) A method as recited in claim 138, wherein terminating comprises:

immersing said first surface in an ammonia-based solution.

142. (Previously Presented) A method as recited in claim 138, comprising:

performing said exposing, cleaning and terminating steps, in order, on said second surface of said second substrate prior to said bonding step.

143. (Previously Presented) A method as recited in claim 138, comprising:

forming a first bonding layer on said first substrate, and

performing said exposing, cleaning and terminating steps on a third surface of said first bonding layer.

144. (Previously Presented) A method as recited in claim 143, comprising: